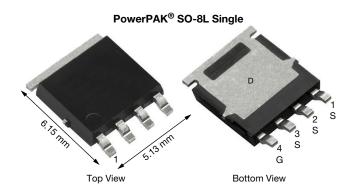


www.vishay.com

Vishay Siliconix

# Automotive N-Channel 80 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY				
V <sub>DS</sub> (V)	80			
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 10 \text{ V}$	0.0135			
I <sub>D</sub> (A)	46			
Configuration	Single			
Package	PowerPAK SO-8L			

#### **FEATURES**

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % Rq and UIS tested
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912





ROHS COMPLIANT HALOGEN FREE

	D
G O	
N-Channel MOSFET	o <sub>s</sub>

<b>ABSOLUTE MAXIMUM RATINGS</b>	$T_C = 25  ^{\circ}C$ , unles	s otherwise noted	l)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V <sub>DS</sub>	80		
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C	I <sub>D</sub>	46		
	T <sub>C</sub> = 125 °C		26.5		
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	50	А	
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	100		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	27		
Single Pulse Avalanche Energy	L = 0.1 MH	E <sub>AS</sub>	36	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C		55	W	
	T <sub>C</sub> = 125 °C		18	VV	
Operating Junction and Storage Temperature Range Soldering Recommendations (Peak Temperature) c, d		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175		
		•	260	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient F	PCB Mount b	$R_{thJA}$	70	°C/W	
Junction-to-Case (Drain)		$R_{thJC}$	2.7	]	

#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. When mounted on 1" square PCB (FR4 material).
- c. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- d. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



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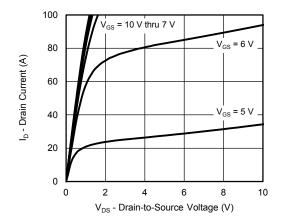
PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static				1			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = 250 \mu A$		80	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_D = 250 \mu A$		3.0	3.5	ľ
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Zero Gate Voltage Drain Current		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 80 V	-	-	1	
	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 80 V, T <sub>J</sub> = 125 °C	-	-	50	μA
		$V_{GS} = 0 V$	V <sub>DS</sub> = 80 V, T <sub>J</sub> = 175 °C	-	-	150	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 \text{ V}$	30	-	-	Α
Drain-Source On-State Resistance a		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A	-	0.0112	0.0135	Ω
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A, T <sub>J</sub> = 125 °C	-	-	0.0208	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A, T <sub>J</sub> = 175 °C	-	-	0.0254	
Forward Transconductance b	9fs	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A		-	40	-	S
Dynamic <sup>b</sup>	•	•					
Input Capacitance	C <sub>iss</sub>			-	1500	2000	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V	$V_{GS} = 0 V$ $V_{DS} = 25 V, f = 1 MHz$	-	800	1100	pF
Reverse Transfer Capacitance	C <sub>rss</sub>	]		-	32	50	
Total Gate Charge <sup>c</sup>	Qg	V <sub>GS</sub> = 10 V	= 10 V V <sub>DS</sub> = 40 V, I <sub>D</sub> = 5 A	-	20	35	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>			-	6	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	3	-	
Gate Resistance	R <sub>g</sub>	f = 1 MHz		0.18	0.37	0.62	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	11	18	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 40 \text{ V}, \text{ R}_L = 8 \Omega$ $I_D \cong 5 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		-	5	10	ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	23	35	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	7	15	
Source-Drain Diode Ratings and Chara	acteristics b						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	100	Α
Forward Voltage	$V_{SD}$	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0		-	0.83	1.2	V

#### **Notes**

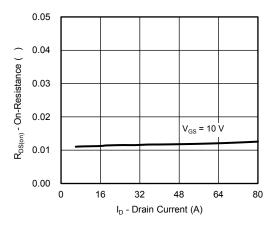
- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

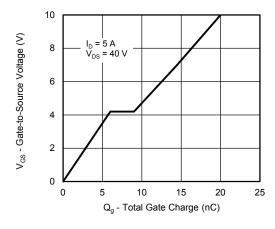




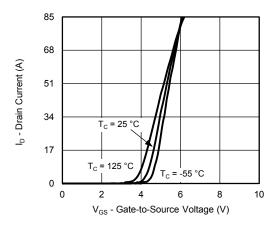
#### **Output Characteristics**



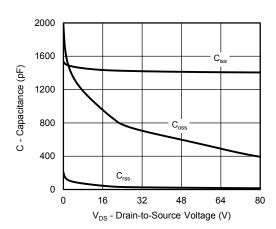
On-Resistance vs. Drain Current



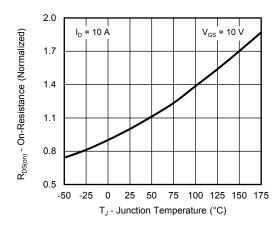
**Gate Charge** 



**Transfer Characteristics** 



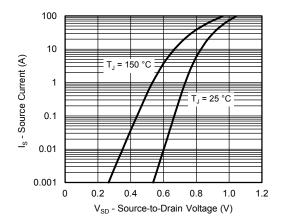
Capacitance



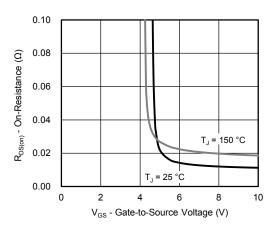
On-Resistance vs. Junction Temperature

For technical questions, contact: automoste

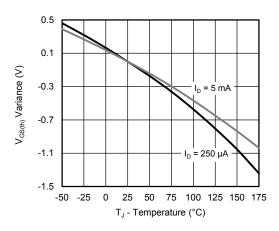




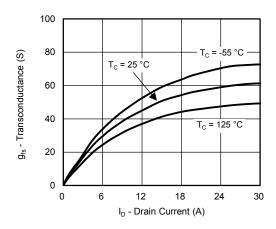
**Source Drain Diode Forward Voltage** 



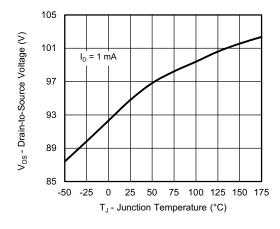
On-Resistance vs. Gate-to Source Voltage



**Threshold Voltage** 

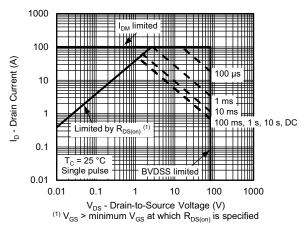


Transconductance

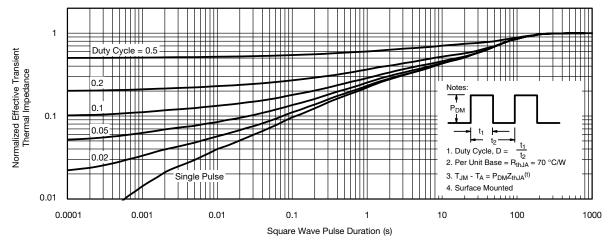


Drain Source Breakdown vs. Junction Temperature



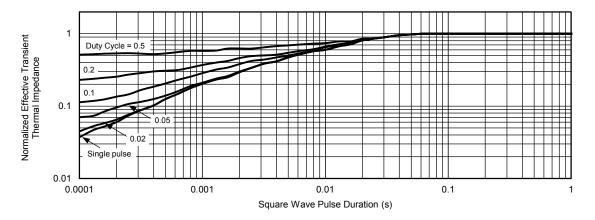


Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient





Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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